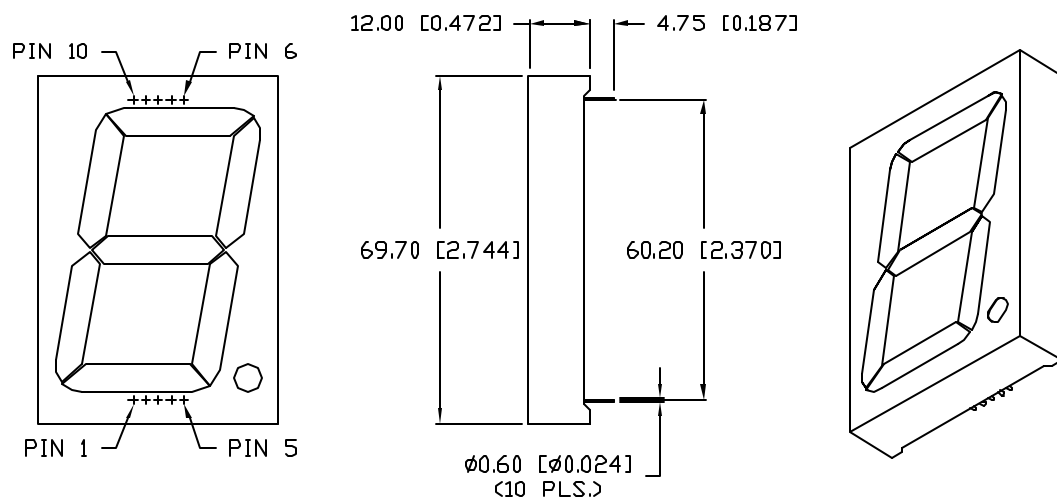


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ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^{\circ}\text{C}$   $I_f=10\text{mA}$

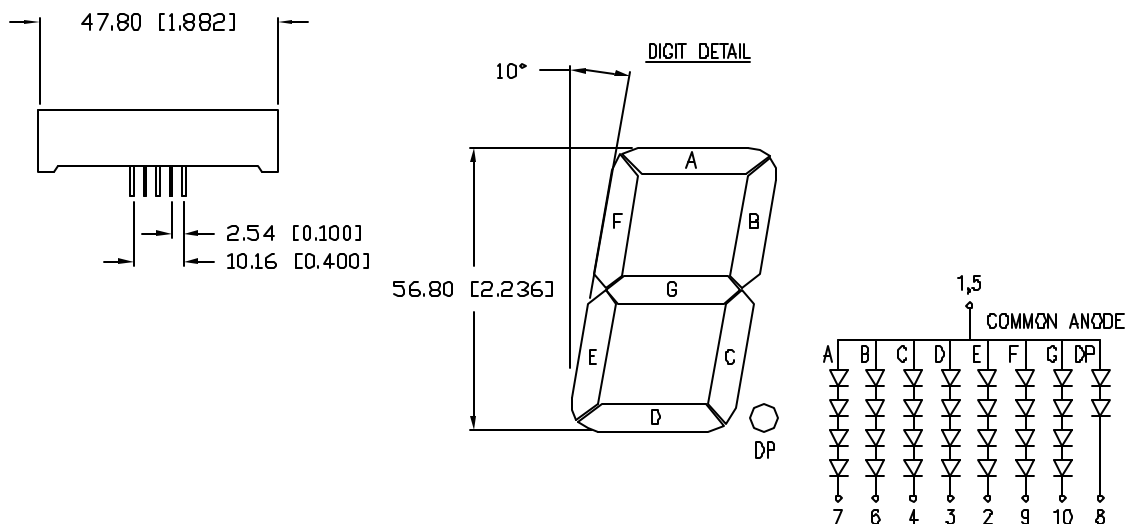
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		636		nm	
FORWARD VOLTAGE *		8.0/4.0	10.0/5.0	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_f=100\mu\text{A}$
AXIAL INTENSITY		13000		$\mu\text{cd}$	$I_f=10\text{mA}$
EMITTED COLOR:	RED				
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

\* SECOND VALUE FOR DOUBLE CHIP IN DECIMAL POINT.

LIMITS OF SAFE OPERATION AT  $25^{\circ}\text{C}$  PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM $25^{\circ}\text{C}$	-1.2	mW/ $^{\circ}\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^{\circ}\text{C}$
SOLDERING TEMP.	+260	$^{\circ}\text{C}$
2.0mm FROM BODY		3 SEC. MAX

\*  $t < 10\mu\text{s}$



\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X= $\pm 1$  ( $\pm 0.039$ ), XX= $\pm 0.5$  ( $\pm 0.020$ ), XXX= $\pm 0.25$  ( $\pm 0.010$ ), XXXX= $\pm 0.127$  ( $\pm 0.005$ ). LEAD SIZE= $\pm 0.05$  ( $\pm 0.002$ ), LEAD LENGTH= $\pm 0.75$  ( $\pm 0.030$ ), MIN=  $\begin{matrix} +\text{DECIMAL PRECISION} \\ -0.00 \end{matrix}$  MAX=  $\begin{matrix} +0.00 \\ -\text{DECIMAL PRECISION} \end{matrix}$

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2.25" SEVEN SEGMENT, SINGLE DIGIT DISPLAY,  
636nm RED CHIPS, GRAY FACE WITH WHITE SEGMENTS,  
COMMON ANODE, 10 PINS.

RELIABILITY NOTE  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC	CHECKED BY:	APPROVED BY:	DATE: 7.3.03
			PAGE: 1 OF 1
			SCALE: N/A